Final Product Change Notification | 201902021F01

Issue Date: 28-Mar-2019
Effective Date: 26-Jun-2019

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QUALITY

Management Summary

BE2 tranferring from ASEK to ATKH (grinding/sawing/marking and packing).
BE2 (back half of the Assembly process) will be enabled in ATKH.

Change Category

[ ] Wafer Fab Process	[ ] Assembly [ ] Product Marking Process	[ ] Test Location	[ ] Design
[ ] Wafer Fab Materials	[ ] Assembly [ ] Mechanical Materials Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly [ ] Location Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage
[ ] Firmware	[X] Other - BE2 process transferring (Grinding/Sawing/Marking/Packing)		

ASEK Grinding/Sawing Transferring to ATKH - NX5P3290

Description of Change

Expanding the current flow which is currently limited to an ASE Assembly to allow for ATKH BE2.
The flow allows for manufacturing flexibility and helps ensure customer supply.
BE2(back half of the Assembly process) (grinding/sawing/marking and Packing) will be enabled in ATKH.
There's no change in Form, Fit or Function.

Reason for Change

Expanding the current flow which is currently limited to an ASE Assembly to allow for ATKH BE2.
The flow allows for manufacturing flexibility and helps ensure customer supply.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information
Samples are available upon request
Production
Planned first shipment 30-Apr-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.
Data Sheet Revision
No impact to existing datasheet
Disposition of Old Products
Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 27-Apr-2019.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

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Affected Part Number	Affected 12NC
NX5P3290UKZ	935307826012